

## PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SAM IDICULA	01/02/2018
KIRTIKAR KASHYAP	12/28/2017
ARUN RAGHAVAN	12/21/2017
EVANGELOS VLACHOS	12/21/2017
VENKATRAMAN GOVINDARAJU	01/25/2018
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<b>Name:</b>	ORACLE INTERNATIONAL CORPORATION
<b>Street Address:</b>	500 ORACLE PARKWAY, MAIL STOP 50P7
<b>City:</b>	REDWOOD SHORES
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	94065
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16670681
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<b>ATTORNEY DOCKET NUMBER:</b>	50277-5601
<b>NAME OF SUBMITTER:</b>	BRIAN N. MILLER
<b>SIGNATURE:</b>	/BrianNMiller#70764/
<b>DATE SIGNED:</b>	04/30/2021
<b>Total Attachments: 2</b>	

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ASSIGNMENT OF APPLICATION FOR PATENT

WHEREAS:

- SAM IDICULA of Santa Clara, California;
- KIRTIKAR KASHYAP of Redwood City, California;
- ARUN RAGHAVAN of Belmont, California;
- EVANGELOS VLACHOS of San Francisco, California; and
- VENKATRAMAN GOVINDARAJU of Fremont, California;

(hereinafter referred to as ASSIGNOR(S)), has made a discovery and/or invention entitled:

**HYBRID INSTRUMENTATION FRAMEWORK FOR MULTICORE LOW POWER PROCESSORS**

- for which application for Letters Patent of the United States has been executed on even date herewith,
- for which application for Letters Patent of the United States has been filed on \_\_\_\_, under Application No. \_\_\_\_, and

WHEREAS:

Oracle International Corporation, a corporation of California, having a business address of 500 Oracle Parkway, Mail Stop 5OP7, Redwood Shores, CA 94065

and which, together with its successors, assigns, and legal representatives, is hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in, to and under said invention and in, to and under Letters Patent or similar legal protection to be obtained therefor in the United States and in any and all foreign countries.

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:

Be it known that for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sells, assigns and transfers to ASSIGNEE, the full and exclusive right, title and interest to said discovery or invention in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the United States and its territorial possessions and in any and all foreign countries to be obtained for said invention by said application or any continuation, continuation-in-part, divisional, reexamination, renewal, substitute, reissue and/or any application claiming priority thereof, including any legal equivalent thereof, in a foreign country for the full term or terms for which the same may be granted.

I, SAID ASSIGNOR(S), hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and any Official of any country or countries foreign to the United States of America whose duty it is to issue Letters Patent on applications as aforesaid, to issue all such Letters Patent for said discovery or invention to the ASSIGNEE, as

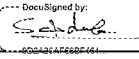
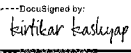


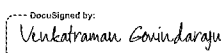
assignee of the entire right, title and interest in, to and under the same, for the sole use and benefit of the ASSIGNEE in accordance with the terms of this instrument.

I, SAID, ASSIGNOR(S), hereby covenant with ASSIGNEE that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned and that I have full right to convey the entire right, title and interest herein sold, assigned, transferred and set over;

AND I, SAID ASSIGNOR(S) hereby further covenant and agree that the ASSIGNEE may apply for foreign Letters Patent on said discovery or invention and claim the benefits of the International Convention, and that I will, at any time, when called upon to do so by the ASSIGNEE communicate to the ASSIGNEE as the case may be, any facts known to me respecting said discovery or invention, and execute and deliver any and all lawful papers that may be necessary or desirable to perfect the title to the said discovery or invention, the said applications and the said Letters Patent in the ASSIGNEE and that if reissues or reexaminations of the said Letters Patent or disclaimers relating thereto, or divisionals, continuations, continuation-in-parts of the said applications shall hereafter be desired by the ASSIGNEE, I will, at any time, when called upon to do so by the ASSIGNEE sign all lawful papers, make all rightful oaths, execute and deliver all such disclaimers and all divisional, continuation, continuation-in-part, reexamination, and reissue applications so desired, and do all lawful acts requisite for the application for such continuations, continuation-in-parts, divisionals, reexaminations, or reissues and the procuring thereof and for the filing of such disclaimers and such applications, and generally do everything possible to aid the ASSIGNEE to obtain and enforce proper patent protection for said invention or discovery in all countries, all without further compensation but at the expense of the ASSIGNEE.

ASSIGNOR hereby authorizes and requests the prosecuting law firm to insert herein above the application number and filing date of said application when known.

**Inventor(s): Please Sign and Date Below:**

- |     |   |                                |
|-----|---|--------------------------------|
| (1) | <br>_____<br>SAM IDICULA             | Date: <u>January 2, 2018</u>   |
| (2) | <br>_____<br>KIRTIKAR KASHYAP        | Date: <u>December 28, 2017</u> |
| (3) | <br>_____<br>ARUN RAGHAVAN           | Date: <u>December 21, 2017</u> |
| (4) | <br>_____<br>EVANGELOS VLACHOS       | Date: <u>December 21, 2017</u> |
| (5) | <br>_____<br>VENKATRAMAN GOVINDARAJU | Date: <u>January 25, 2018</u>  |